

Docket No.: 50352-020

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Shiroshi MATSUKI, et al.

Serial No.: 09/944,344

Filed: September 04, 2001

Group Art Unit: 1741

Examiner: *Leader*

For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR MANUFACTURING
SAME AND COPPER ELECTROPLATING METHOD

INFORMATION DISCLOSURE STATEMENT

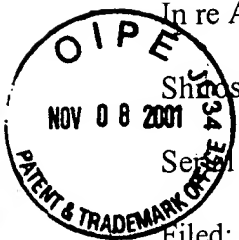
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

The relevance of each non-English language reference, if any, is discussed in the present specification.



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Attached to each non-English language reference is an English Abstract.

Respectfully submitted,

MCDERMOTT, WILL & EMERY



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